

# 1.2 MP Smart iToF 1/3.2-inch Stacked BSI Global Shutter Depth Sensor

## Product Preview

### AF0130, AF0131

onsemi AF0130 and AF0131 Smart Indirect Time of Flight (iToF) sensors are a 1/3.2-inch optical format, back side illuminated (BSI) CMOS global shutter depth and imaging solution. The sensors have on-chip dual laser driver controls and modulation frequencies (up to 200 MHz) as well as on-chip laser eye-safety thresholds.

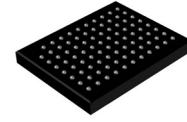
The AF0130 sensor version comes with a depth processing ASIC stacked below its pixel area which calculates depth, confidence and intensity maps at high speeds from its laser modulated exposures.

The AF0131 sensor version does not come with on-chip depth processing but does come with the same performance. This sensor is for solutions which prefer their own depth calculations off-chip.

**Table 1. KEY PERFORMANCE PARAMETERS**

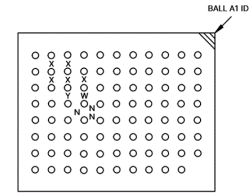
| Parameter                           | Typical Value  |
|-------------------------------------|--|
| Optical Format                      | 1/3.2 inch (5.60 mm Diagonal, 4:3 Aspect Ratio)  |
| Active Pixels                       | 1280 x 960   |
| Pixel Size                          | 3.5 $\mu\text{m}$  |
| Chief Ray Angle                     | 30°  |
| Shutter Type                        | BSI Global Shutter   |
| One-Time Programmable Memory (OTPM) | 3 instances of 1024 x 24 bits  |
| Input Clock Range                   | 10–30 MHz  |
| Interface                           | – Data: MIPI (2 Lanes, 2 Gbps/lane)<br>– Host Two-Wire / Four-Wire<br>– Laser Driver Three-Wire<br>– Laser Modulation: LVDS      |
| ADC Resolution                      | 10–11 bit  |
| Analog Gain Range                   | 1–4x gain  |
| Frame Rate                          | Mode 2.2 (Single Frequency):<br>Max 60 fps @ 1.2 MP,<br>Max 100 fps @ VGA  |
| Read Noise                          | <5 e <sup>-</sup> with on-chip memory (C <sub>1,4</sub> )<br><3.5 e <sup>-</sup> from storage gates (SG <sub>1,2</sub> )         |
| Binning                             | 2x2, 4x4   |
| SNR <sub>MAX</sub>                  | TBD dB   |
| Dynamic Range                       | TBD dB   |
| Supply Voltage I/O Digital Analog   | 1.2 V, 1.8 V, 2.8 V  |
| Power Consumption (Note 1)          | 400 mW in Mode2.2 (100 MHz) @<br>30 fps and 0.35 ms exposure<br>600 mW in Mode3.2 (100+120 MHz)<br>@ 30 fps and 0.35 ms exposure |
| Operating Temperature               | (–30°C < T <sub>J</sub> < +85°C)   |
| Optimal Performance Temperature     | (0°C < T <sub>J</sub> < +60°C)   |
| Package Options                     | – 6.06 mm x 4.84 mm 11x8 pin Ball CSP package, 0.5 mm ball pitch<br>– Bare Die   |
| $\theta_{JA}$ : °C/W (Note 2)       | 32.0   |
| $\theta_{JB}$ : °C/W                | 10.0   |

- Power consumption will increase with exposure time and modulation frequency.
- $\theta_{JA}$  is dependent on the customer module design and should not be used for calculating junction temperature.



ODCSP87 6.05x4.83x0.63, 0.50P  
CASE 570AZ

### MARKING DIAGRAM



XXXX = Specific Device Code  
Y = Year  
W = Work Week  
NNN = Serial Number

### ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

## Non-NDA Data Sheet

**Interested in what you see?** If you would like more detailed information, please request the full version of our data sheet.

[Request Full Data Sheet](#)

## AF0130, AF0131

### Features

- 1.2 MP CMOS Smart iToF Sensor with Advanced 3.5  $\mu\text{m}$  Pixel Stacked BSI Technology
- Superior Low-Light and Ambient-Light Performance
- Enhanced NIR Response at 850 nm and 940 nm Wavelength (QE > 40%)
- Dual Laser (Frequency) Operation for Increased Depth Range (Disambiguation) in VGA Resolution
- Low Voltage Differential Signal (LVDS) Driver for Modulation Control of 2 Lasers up to 200 MHz
- Two or Four-Wire Serial Interface for Register Access
- 2 Gbps/Lane, 2-lane MIPI CSI-2 D-PHY Data Interface
- Laser Eye Safety Monitoring
- Three Output Mode: RAW, Data Reduction (DR), Integrated Depth Processing (DP)
- Phase and Pulsed (Hybrid) Modulation Support
- Simultaneous Depth, Confidence and Grayscale Output
- Horizontal and Vertical Mirroring, Windowing and Pixel Binning
- Context State Machine with 64 Programmable Contexts

- Automatic Exposure Control (AEC)
- Pixel Identification & Correction (PDI & PDC)
- Multi Camera and Interference Mitigation
- Reduced Motion Artefacts due to Decoupling between Integration and Readout
- Hardware Trigger Control
- On-Chip Mean and Histogram Statistics for Smart Control
- On-Chip Temperature Sensor
- These Devices are Pb-Free and RoHS Compliant

### Applications

- Computing
- Drones, Robotics & Automation
- Metrology
- Machine Vision
- Future Retail & Intelligent Logistics
- Security & Access Control
- Virtual or Augmented Reality
- 3D Modeling

**Table 2. ORDERING INFORMATION – PART**

| Part Number            | Product Description   | On-chip Depth Processing | Protective Film |
|------------------------|---|--------------------------|-----------------|
| AF0130CS1M30SMKA1-CP-E | AF0130 REV2 Engineering Samples (AF0131 + Depth, Confidence & Visual) | yes                      | yes             |
| AF0131CS1M30SMKA1-CP-E | AF0131 REV2 Engineering Samples (RAW, DR, 1.2 MP, 30° CRA)            | no                       | yes             |
| AF0130CS1M30SMKA1-CR-E | AF0130 REV2 Engineering Samples (AF0131 + Depth, Confidence & Visual) | yes                      | no              |
| AF0131CS1M30SMKA1-CR-E | AF0131 REV2 Engineering Samples (RAW, DR, 1.2 MP, 30° CRA)            | no                       | no              |

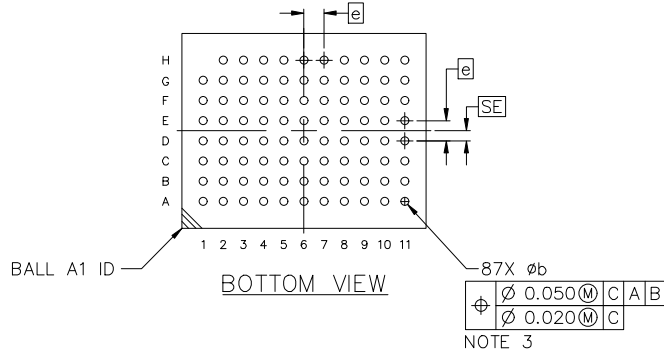
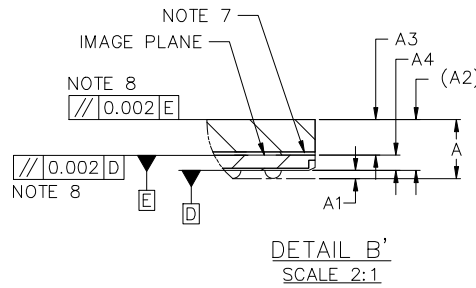
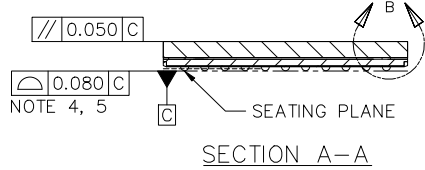
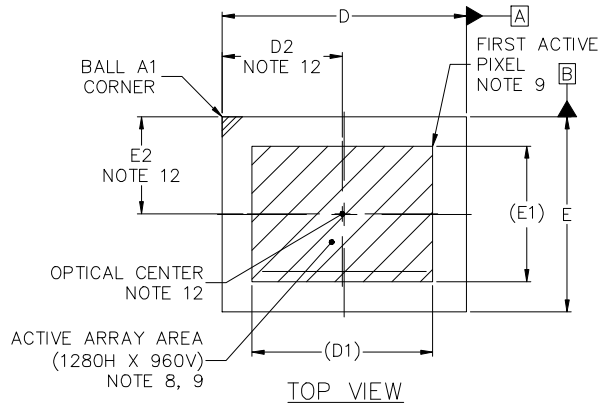
**Table 3. ORDERING INFORMATION – EVALUATION BOARD**

| Part Number             | Product Description   |
|-------------------------|---|
| AF0130CSSM30SMKAH3-GEVK | AF0130 Sensor Headboard + Lens (940nm filter, 65° HFOV)       |
| AGBENECS-GEVK           | Laser Headboard (4 VCSEL's, 60° HFOI)                         |
| AGB1N0CS-GEVK           | Demo 3 Board (FPGA Base Board including USB Cable and Tripod) |

# AF0130, AF0131

## PACKAGE DIMENSIONS

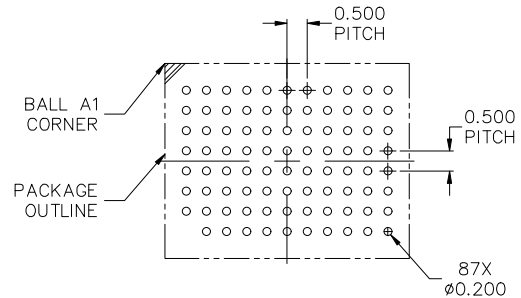
### ODCSP87 6.05x4.83x0.63, 0.50P CASE 570AZ ISSUE A



**NOTES:**

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52.
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.040 THICKNESS.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS  $\pm 0.1^\circ$ .
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
11. PACKAGE CENTER (X, Y) = (0.000, 0.000).
12. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (-0.046, 0.012).

| DIM | MILLIMETERS |       |       |
|-----|-------------|-------|-------|
|     | MIN.        | NOM.  | MAX.  |
| A   | ---         | ---   | 0.762 |
| A1  | 0.081       | 0.101 | 0.121 |
| A2  | 0.631 REF.  |       |       |
| A3  | 0.425       | 0.440 | 0.455 |
| A4  | 0.171       | 0.191 | 0.211 |
| b   | 0.184       | 0.204 | 0.224 |
| D   | 6.030       | 6.055 | 6.080 |
| D1  | 4.480 REF.  |       |       |
| D2  | 2.956       | 2.981 | 3.006 |
| E   | 4.810       | 4.835 | 4.860 |
| E1  | 3.360 REF.  |       |       |
| E2  | 2.380       | 2.405 | 2.430 |
| e   | 0.500 BSC   |       |       |



\*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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